

TVS Diodes Axial Leaded - 15kA > KD Series

Description

The KD Series of high powerTVS diode is specially designed for meeting severe surge test environment of both AC and DC line protection applications. It features a very fast response and ultra low clamping characteristics over traditional metal oxide (MOV) solutions. They can be connected in series and / or parallel to create a very high surge current protection solution..

- Very low clamping voltage
- Ultra compact: less than one-tenth the size of traditional discrete solutions
- Sharp breakdown voltage
- · Low slope resistance
- Bi-directional
- Foldbak technology for superior clamping factor
- Symmetric in leads width for easier soldering during assembly.
- IEC-61000-4-2 ESD 15kV(Air), 8kV (Contact)

- ESD protection of data lines in accordance with IEC 61000-4-2
- EFT protection of data lines in accordance with IEC 61000-4-4
- Halogen-free
- RoHS compliant
- Glass passivated junction
- Pb-free E4 means 2nd level interconnect is Pb-free and the terminal finish material is Silver



Maximum Ratings andThermal Characteristics (TA=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Operating Junction and StorageTemperature Range	TJ ,TSTG	(-)55 to125	°C
Current Rating1	PP	15	kA

Note: 1. Rated Ipp with 8/20µs pulse.

Functional Diagram

Cathode Anode

Electrical Characteristics (T_A=25°C unless otherwise noted)

		e Stand- oltage	Breakdown Voltage	Test Current	Current Rating	Maximum Clamping Voltage	Reverse Leakage
Part Number	VAC	VDC	Min. Ver @ It	lτ	Ipp @ 8/20µs	Vc @ Ipp	IR @Vdc
	(V)	(V)	(V)	(mA)	(kA)	(V)	(μΑ)
KD-025C	17	25	28	10	15	95	2
KD-030C	21	30	33	10	15	100	2
KD-042C	30	42	47	10	15	105	2
KD-058C	40	58	64	10	15	110	2
KD-066C	45	66	70	10	15	120	2
KD-076C	54	76	85	10	15	140	2
KD-150C	105	150	165	10	15	240	2
KD-170C	130	170	180	10	15	260	2
KD-190C	145	190	200	10	15	290	2
KD-200C	150	200	222	10	15	330	2



Physical Specifica	ations
Weight	Contact manufacturer
Case	Epoxy encapsulated
Terminal	Silver plated leads, solderable per MIL-STD-750 Method 2026

Flow/Wave Soldering (Solder Dipping)Peak Temperature :265°CDipping Time :10 secondsSoldering :1 time

Wave Solder Profile

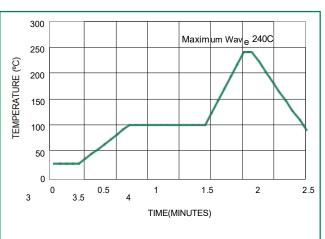
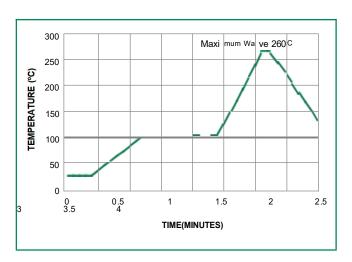


Figure 2 - Lead-free Profile



Ratings and Characteristic Curves (T_A=25°C unless otherwise noted)

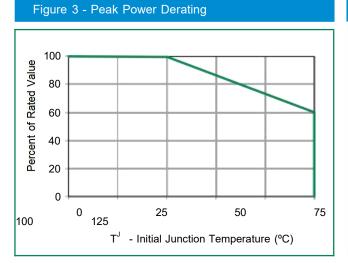


Figure 4 - Surge Response

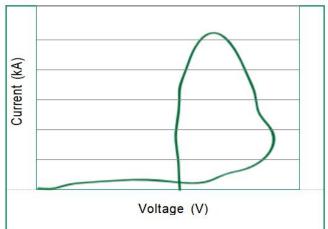


Figure 1 - Non Lead-free Profile



KD Series

Ratings and Characteristic Curves (TA=25°C unless otherwise noted) (Continued)

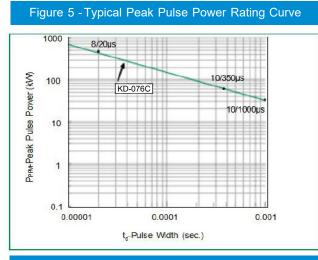


Figure 7 -Surge Response (8/20 Surge current waveform)

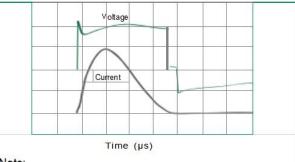
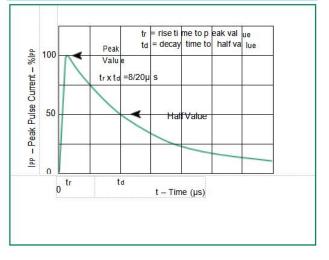


Figure 6 - Typical VBR Vs Junction Temperature 12 10 8 Percent of VBR Change 6 4 2 0 -2 -4 -6 -8 100 125 -50 -25 0 25 50 75 Junction Temperature(T,)

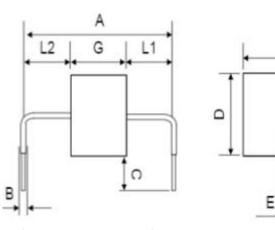


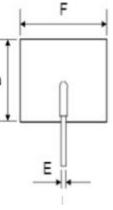


Note:

The power dissipation causes a change in avalanche voltage during the surge and the avalanche voltage eventually returns to the original value when the transient has passed.

Dimensions





КDЛ	です图	
Ref. (mm)	Millimeters	
A	24.15±1.00	
В	2.4 \pm 0.60	
С	6. OMIN	
D	16. OMAX	
E	1.28+0.02	
F	16.0MAX	
G-030	6. OMAX	
G-058/66/076	8. OMAX	
G150/170/190/200	15MAX	
L1=L2 toler:	ance±1.2mm	